



High Power Monolithic OPERATIONAL AMPLIFIER

FEATURES

- POWER SUPPLIES TO $\pm 40\text{V}$
- OUTPUT CURRENT TO 10A PEAK
- PROGRAMMABLE CURRENT LIMIT
- INDUSTRY-STANDARD PIN OUT
- FET INPUT
- TO-3 AND LOW-COST POWER PLASTIC PACKAGES

APPLICATIONS

- MOTOR DRIVER
- SERVO AMPLIFIER
- SYNCHRO EXCITATION
- AUDIO AMPLIFIER
- PROGRAMMABLE POWER SUPPLY

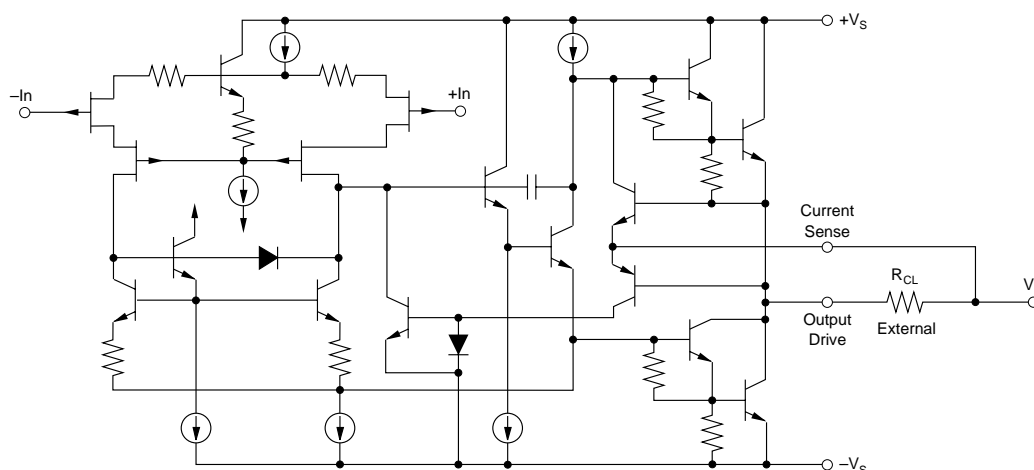
DESCRIPTION

The OPA541 is a power operational amplifier capable of operation from power supplies up to $\pm 40\text{V}$ and delivering continuous output currents up to 5A. Internal current limit circuitry can be user-programmed with a single external resistor, protecting the amplifier and load from fault conditions. The OPA541 is fabricated using a proprietary bipolar/FET process.

Pinout is compatible with popular hybrid power amplifiers such as the OPA511, OPA512 and the 3573. The OPA541 uses a single current-limit resistor to set both the positive and

negative current limits. Applications currently using hybrid power amplifiers requiring two current-limit resistors need not be modified.

The OPA541 is available in an 11-pin power plastic package and an industry-standard 8-pin TO-3 hermetic package. The power plastic package has a copper-lead frame to maximize heat transfer. The TO-3 package is isolated from all circuitry, allowing it to be mounted directly to a heat sink without special insulators.



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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

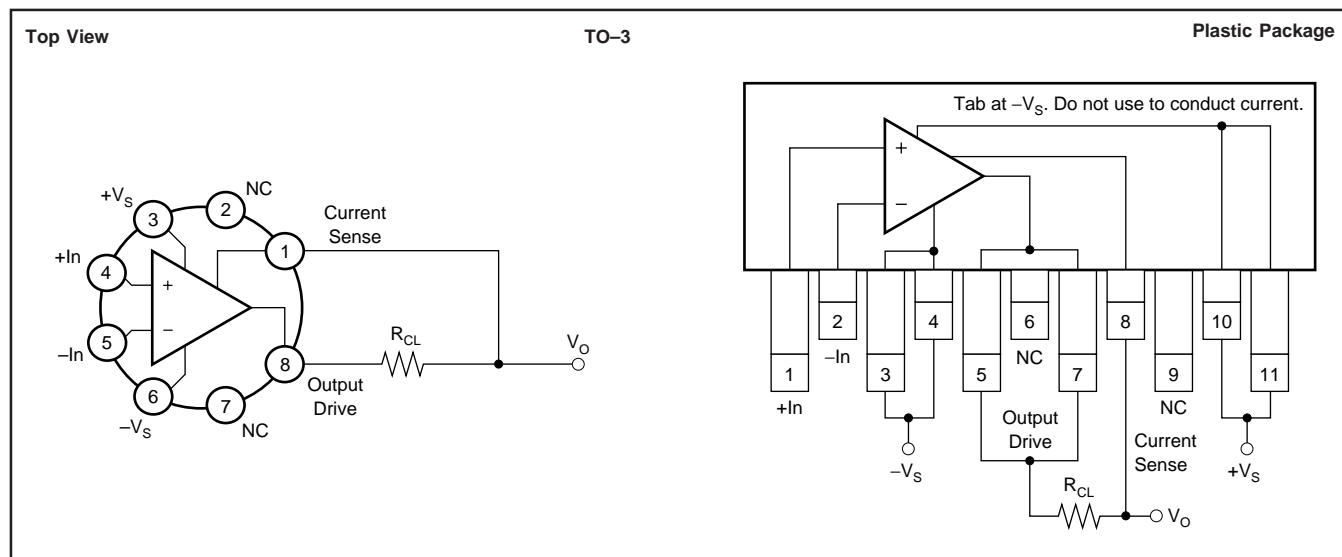
Supply Voltage, $+V_S$ to $-V_S$	80V
Output Current	see SOA
Power Dissipation, Internal ⁽²⁾	125W
Input Voltage: Differential	$\pm V_S$
Common-mode	$\pm V_S$
Temperature: Pin solder, 10s	+300°C
Junction ⁽²⁾	+150°C
Temperature Range:	
AM, BM SM	
Storage	-65°C to +150°C
Operating (case)	-55°C to +125°C
AP	
Storage	-40°C to +85°C
Operating (case)	-25°C to +85°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. (2) Long term operation at the maximum junction temperature will result in reduced product life. Derate internal power dissipation to achieve high MTTF.

PACKAGE/ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

CONNECTION DIAGRAMS



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ELECTRICAL CHARACTERISTICS

At $T_C = +25^\circ\text{C}$ and $V_S = \pm 35\text{VDC}$, unless otherwise noted.

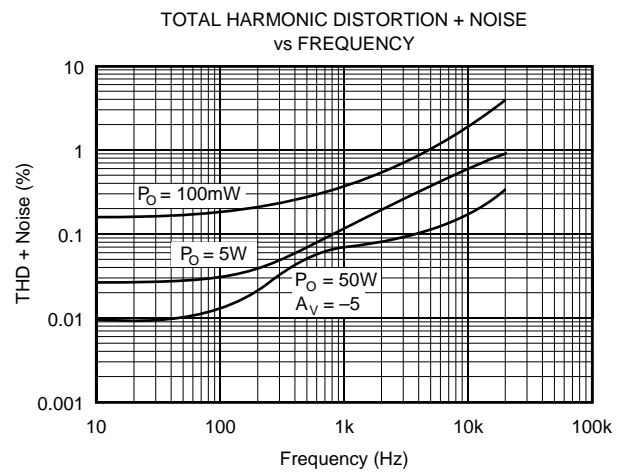
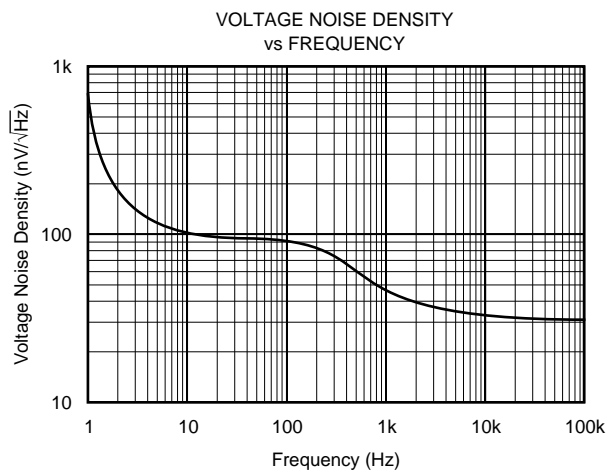
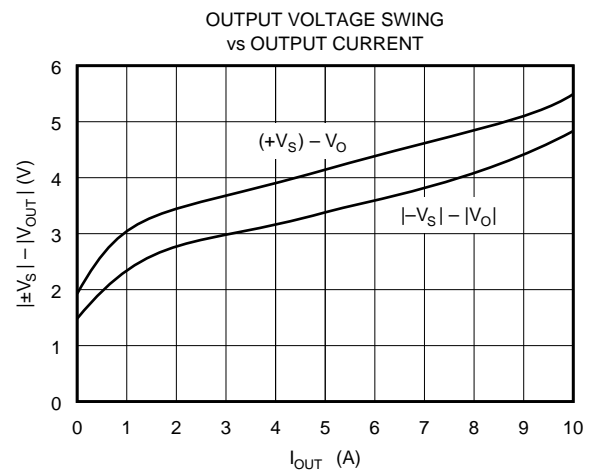
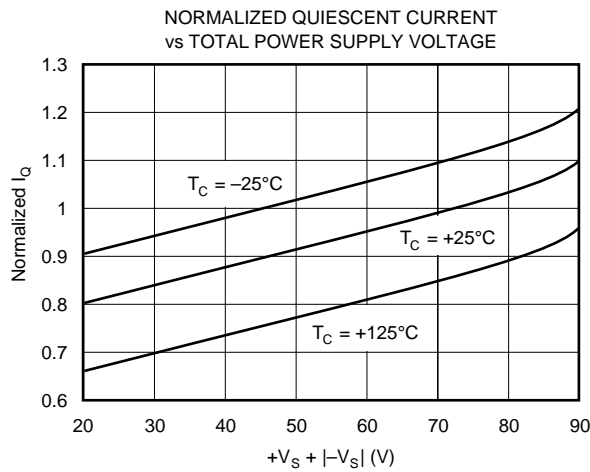
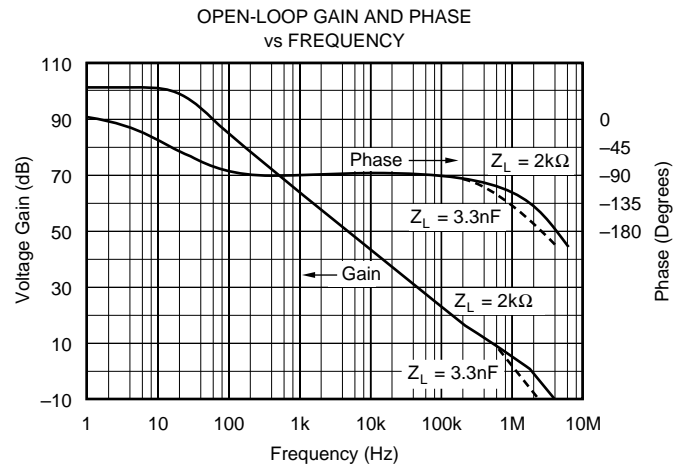
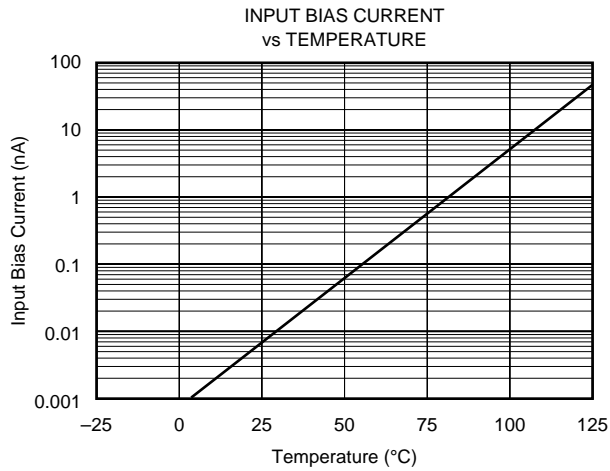
PARAMETER	CONDITIONS	OPA541AM/AP			OPA541BM/SM			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
INPUT OFFSET VOLTAGE V_{OS} vs Temperature vs Supply Voltage vs Power	Specified Temperature Range $V_S = \pm 10\text{V}$ to $\pm V_{MAX}$		± 2 ± 20 ± 2.5 ± 20	± 10 ± 40 ± 10 ± 60		± 0.1 ± 15 * *	± 1 ± 30 * *	mV $\mu\text{V}/^\circ\text{C}$ $\mu\text{V/V}$ $\mu\text{V/W}$
INPUT BIAS CURRENT I_B			4	50		*	*	pA
INPUT OFFSET CURRENT I_{OS}	Specified Temperature Range		± 1	± 30 5		* *	* *	pA nA
INPUT CHARACTERISTICS Common-Mode Voltage Range Common-Mode Rejection Input Capacitance Input Impedance, DC	Specified Temperature Range $V_{CM} = (V_S - 6\text{V})$	$\pm(V_S - 6)$ 95	$\pm(V_S - 3)$ 113 5 1		* *	* * * *		V dB pF $T\Omega$
GAIN CHARACTERISTICS Open Loop Gain at 10Hz Gain-Bandwidth Product	$R_L = 6\Omega$	90	97 1.6		*	* *		dB MHz
OUTPUT Voltage Swing Current, Peak	$I_O = 5\text{A}$, Continuous $I_O = 2\text{A}$ $I_O = 0.5\text{A}$	$\pm(V_S - 5.5)$ $\pm(V_S - 4.5)$ $\pm(V_S - 4)$ 9	$\pm(V_S - 4.5)$ $\pm(V_S - 3.6)$ $\pm(V_S - 3.2)$ 10		* * * *	* * * *		V V V A
AC PERFORMANCE Slew Rate Power Bandwidth Settling Time to 0.1% Capacitive Load Phase Margin	$R_L = 8\Omega$, $V_O = 20\text{Vrms}$ 2V Step Specified Temperature Range, $G = 1$ Specified Temperature Range, $G > 10$ Specified Temperature Range, $R_L = 8\Omega$	6 45 3.3	10 55 2 40	 SOA ⁽¹⁾	* * *	* * * *	 * *	V/ μs kHz μs nF Degrees
POWER SUPPLY Power Supply Voltage, $\pm V_S$ Current, Quiescent	Specified Temperature Range	± 10	± 30 20	± 35 25	*	± 35 *	± 40 *	V mA
THERMAL RESISTANCE θ_{JC} (Junction-to-Case) ⁽²⁾ $\theta_{JC}^{(2)}$ θ_{JA} (Junction-to-Ambient) OPA541AP (Plastic)	AC Output $f > 60\text{Hz}$ DC Output No Heat Sink		2.5 3 40 40					$^\circ\text{C/W}$ $^\circ\text{C/W}$ $^\circ\text{C/W}$ $^\circ\text{C/W}$
TEMPERATURE RANGE T_{CASE}	AM, BM, AP SM	-25		+85	* -55		* +125	$^\circ\text{C}$ $^\circ\text{C}$

* Specification same as OPA541AM/AP.

NOTE: (1) SOA is the Safe Operating Area shown in Figure 1. (2) Plastic package may require insulator which typically adds 1°C/W .

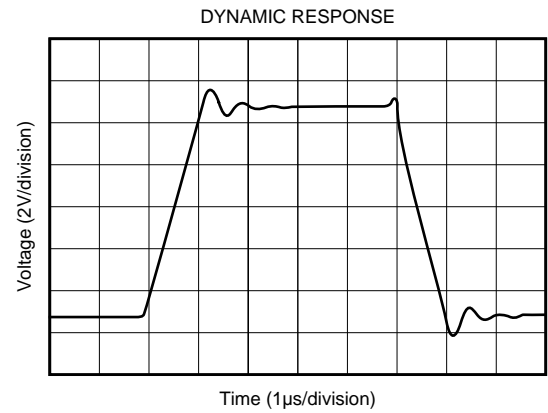
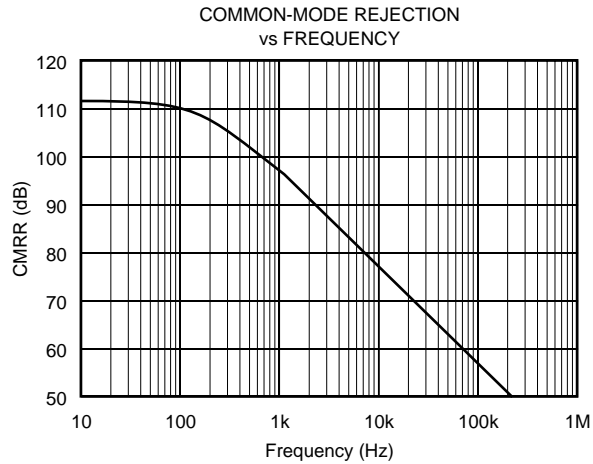
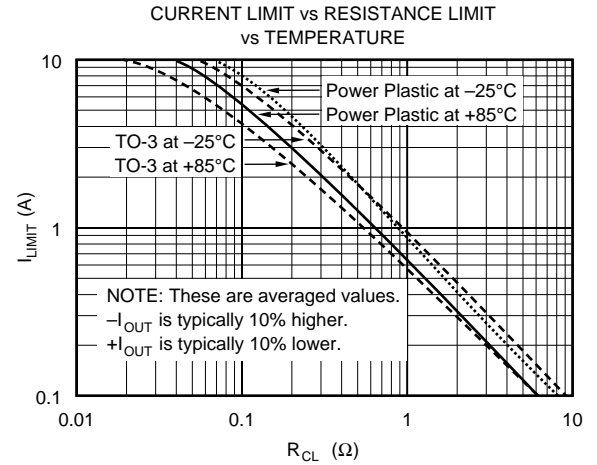
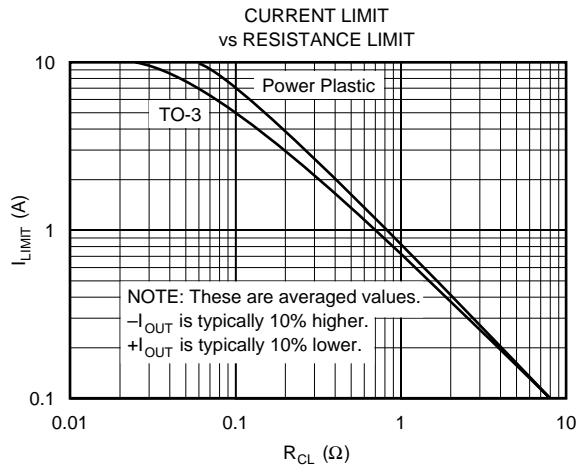
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = \pm 35\text{VDC}$, unless otherwise noted.



TYPICAL CHARACTERISTICS (Cont)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 35\text{VDC}$, unless otherwise noted.



INSTALLATION INSTRUCTIONS

POWER SUPPLIES

The OPA541 is specified for operation from power supplies up to $\pm 40\text{V}$. It can also be operated from unbalanced power supplies or a single power supply, as long as the total power supply voltage does not exceed 80V . The power supplies should be bypassed with low series impedance capacitors such as ceramic or tantalum. These should be located as near as practical to the amplifier's power supply pins. Good power amplifier circuit layout is, in general, like good high frequency layout. Consider the path of large power supply and output currents. Avoid routing these connections near low-level input circuitry to avoid waveform distortion and oscillations.

CURRENT LIMIT

Internal current limit circuitry is controlled by a single external resistor, R_{CL} . Output load current flows through this external resistor. The current limit is activated when the voltage across this resistor is approximately a base-emitter turn-on voltage. The value of the current limit resistor is approximately:

$$\begin{aligned} \text{(AM, BM, SM)} \quad R_{CL} &= \frac{0.809}{|I_{LIM}|} - 0.057 \\ \text{(AP)} \quad R_{CL} &= \frac{0.813}{|I_{LIM}|} - 0.02 \end{aligned}$$

Because of the internal structure of the OPA541, the actual current limit depends on whether current is positive or negative. The above R_{CL} gives an average value. For a given R_{CL} , $+I_{OUT}$ will actually be limited at about 10% below the expected level, while $-I_{OUT}$ will be limited about 10% above the expected level.

The current limit value decreases with increasing temperature due to the temperature coefficient of a base-emitter junction voltage. Similarly, the current limit value increases at low temperatures. Current limit versus resistor value and temperature effects are shown in the Typical Performance Curves. Approximate values for R_{CL} at other temperatures may be calculated by adjusting R_{CL} as follows:

$$\Delta R_{CL} = \frac{-2\text{mV}}{|I_{LIM}|} \times (T - 25)$$

The adjustable current limit can be set to provide protection from short circuits. The safe short-circuit current depends on power supply voltage. See the discussion on Safe Operating Area to determine the proper current limit value.

Since the full load current flows through R_{CL} , it must be selected for sufficient power dissipation. For a 5A current limit on the TO-3 package, the formula yields an R_{CL} of 0.105Ω (0.143Ω on the power plastic package due to different internal resistances). A continuous 5A through 0.105Ω would require an R_{CL} that can dissipate 2.625W .

Sinusoidal outputs create dissipation according to rms load current. For the same R_{CL} , AC peaks would still be limited to 5A , but rms current would be 3.5A , and a current limiting resistor with a lower power rating could be used. Some applications (such as voice amplification) are assured of signals with much lower duty cycles, allowing a current resistor with a low power rating. Wire-wound resistors may be used for R_{CL} . Some wire-wound resistors, however, have excessive inductance and may cause loop-stability problems. Be sure to evaluate circuit performance with the resistor type planned for production to assure proper circuit operation.

HEAT SINKING

Power amplifiers are rated by case temperature, not ambient temperature as with signal op amps. Sufficient heat sinking must be provided to keep the case temperature within rated limits for the maximum ambient temperature and power dissipation. The thermal resistance of the heat sink required may be calculated by:

$$\theta_{HS} = \frac{T_{CASE} - T_{AMBIENT}}{P_D \text{ (max)}}$$

Commercially available heat sinks often specify their thermal resistance. These ratings are often suspect, however, since they depend greatly on the mounting environment and air flow conditions. Actual thermal performance should be verified by measurement of case temperature under the required load and environmental conditions.

No insulating hardware is required when using the TO-3 package. Since mica and other similar insulators typically add approximately 0.7°C/W thermal resistance, their elimination significantly improves thermal performance. See Application Bulletin SBOA021, available for download at www.ti.com, for further details on heat sinking. On the power plastic package, the metal tab may have a high or low impedance connection to $-V_S$. The case should be allowed to float and will likely assume the potential of $-V_S$. Current should **NOT** be conducted through the case.

SAFE OPERATING AREA

The safe operating area (SOA) plot provides comprehensive information on the power handling abilities of the OPA541. It shows the allowable output current as a function of the voltage across the conducting output transistor (see Figure 1). This voltage is equal to the power supply voltage minus the output voltage. For example, as the amplifier output swings near the positive power supply voltage, the voltage



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
OPA541-W	ACTIVE	WAFERSALE	YS	0		TBD	Call TI	Call TI			Samples
OPA541AM	NRND	TO-3	LMF	8	1	Pb-Free (RoHS Exempt)	NI	N / A for Pkg Type		OPA541AM	
OPA541AM-BI	NRND	ZZ (BB)	ZZ030	8		TBD	Call TI	Call TI			
OPA541AP	ACTIVE	TO-220	KV	11	25	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-25 to 85	OPA541AP	Samples
OPA541APG3	ACTIVE	TO-220	KV	11	25	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-25 to 85	OPA541AP	Samples
OPA541BM	NRND	TO-3	LMF	8	18	Pb-Free (RoHS Exempt)	NI	N / A for Pkg Type		OPA541BM	
OPA541SM	NRND	TO-3	LMF	8	18	Pb-Free (RoHS Exempt)	NI	N / A for Pkg Type		OPA541 OPA541SM	
OPA541SM-BI	OBSOLETE	TO-3	LMF	8		TBD	Call TI	Call TI			

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

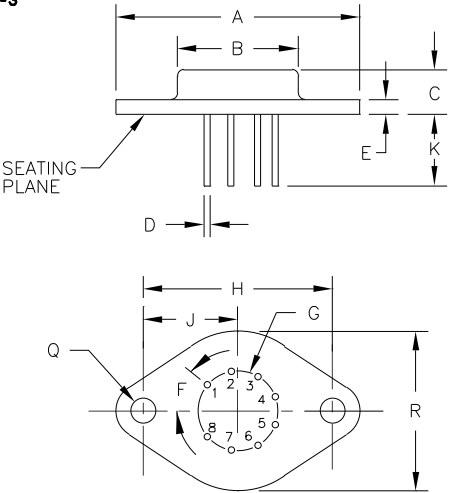
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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Package Number 030 - 8-Pin Metal TO-3

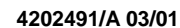


DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	
A	1.510	1.550	38.35	39.37	
B	.745	.770	18.92	19.56	
C	.260	.300	6.60	7.62	
D	.038	.042	0.97	1.07	
E	.080	.105	2.03	2.67	
F	40°	BASIC	40°	BASIC	
G	.500	BASIC	12.70	BASIC	
H	1.182	1.192	30.02	30.28	
J	.591	.596	15.01	15.14	
K	.400	.500	10.16	12.70	
Q	.151	.161	3.84	4.09	
R	.980	1.020	24.89	25.91	

- NOTES:
- LEADS IN TRUE POSITION WITHIN .010" (.25mm) @ MMC AT SEATING PLANE.
 - PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.

PACKAGE NUMBER: ZZ030	REV.: C
JEDEC NUMBER: UNKNOWN	

METAL CYLINDRICAL PACKAGE

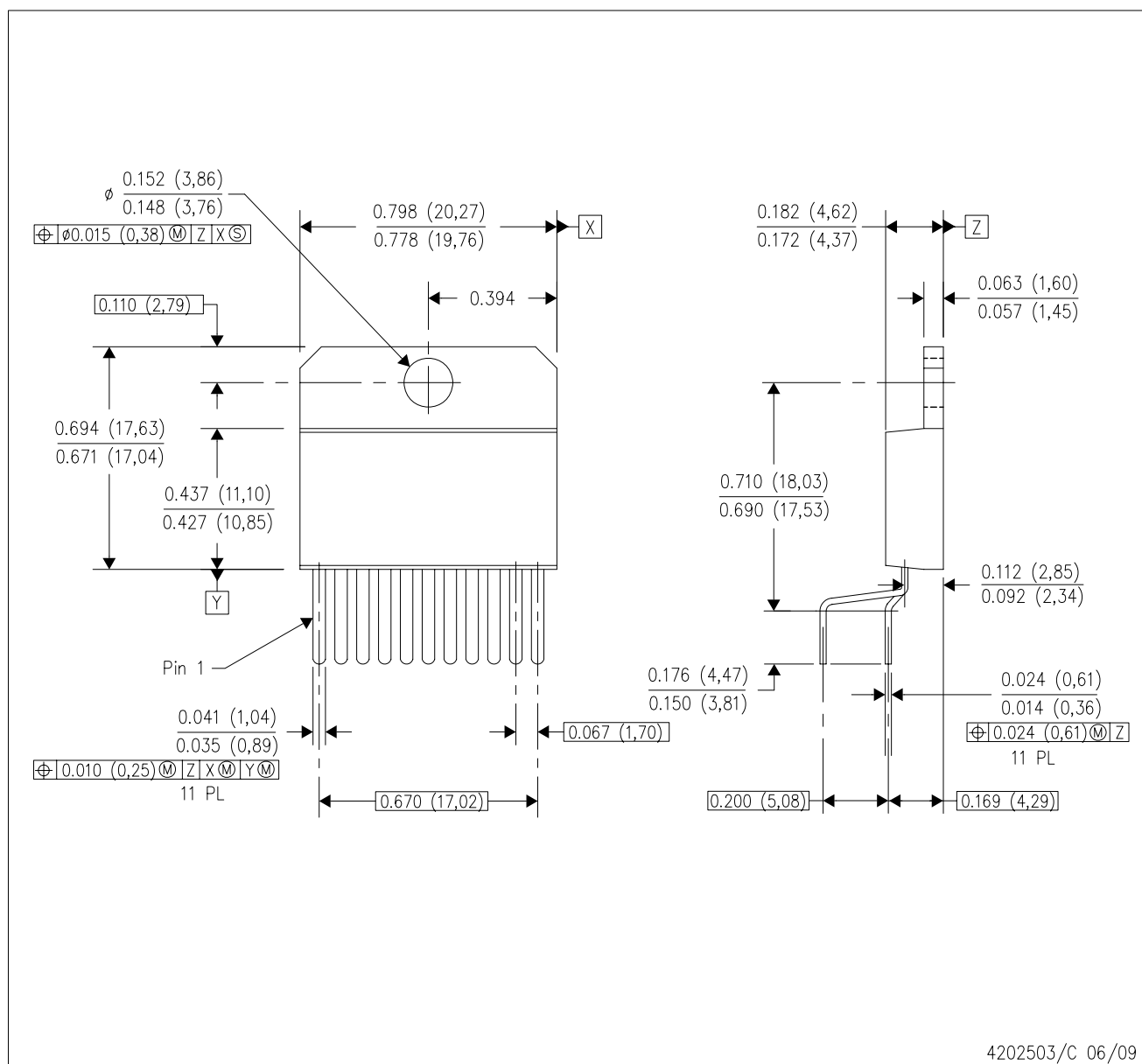


- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Leads in true position within 0.010 (0,25) R @ MMC at seating plane.
D. Pin numbers shown for reference only. Numbers may not be marked on package.

MECHANICAL DATA

KV (R-PZFM-T11)

PLASTIC FLANGE-MOUNT



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Controlling dimension: inch.
 - D. All lead dimensions apply before solder dip.
 - E. Falls within JEDEC MO-48-AA.

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